

MICROSECTIONING ANALYSIS

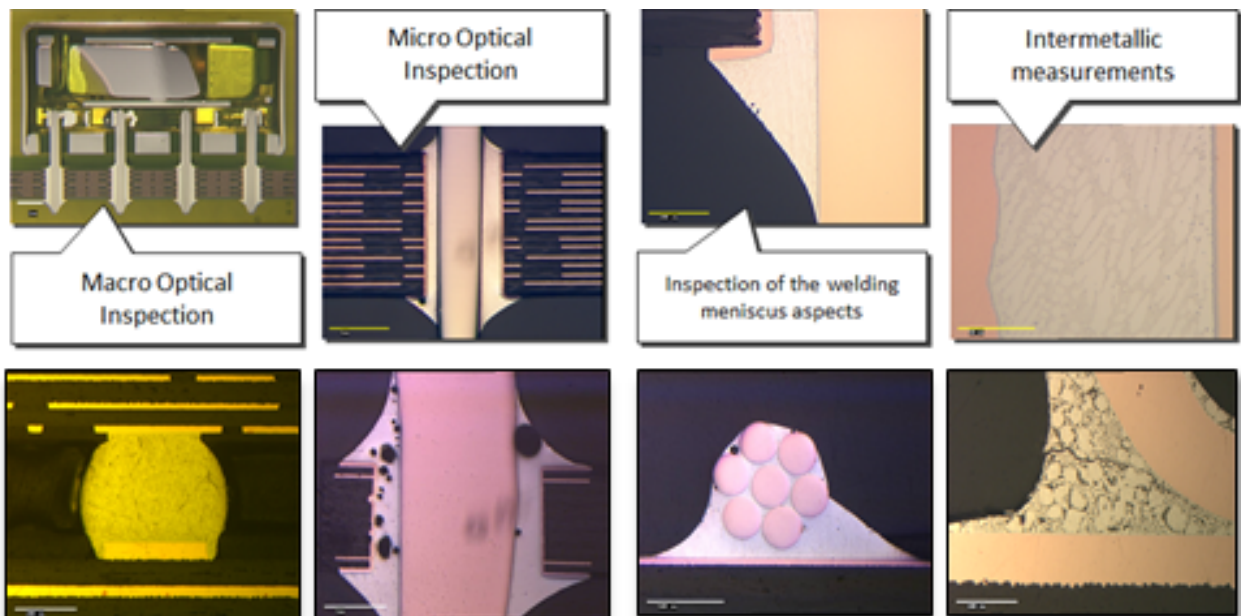
MICROSECTIONING inspection is performed in order to evaluate carefully the PCB raw innerlayers, internal solder joint integrity and devices internal structure. So as it is the most reliable tool to reveal the morphology of the solder joints with respect to intermetallic formation, wetting, cracking and voiding.



PROCESS

Microsectioning or Cross-sectioning is a failure analysis technique, consists of sawing, grinding, polishing, an staining the specimen until the plane of interest is ready for inspection by optical microscopy, in order to judge any defects against the criteria of the specification.

RESULTS



MICROSECTIONING ANALYSIS

OUR GOAL IS

- Find weaknesses of your product and fix them
- Increase your product reliability
- Reduce your time and your cost control of after sales services with mature and more reliable products
- Client's satisfaction
- Improve or preserve your brand image

EQUIPMENT

Cross Section Laboratory :

Diamond head cutter

Polisher

Optical binocular Zoom 64

Optical microscope Zoom 2950



4 x Climatic Chambers



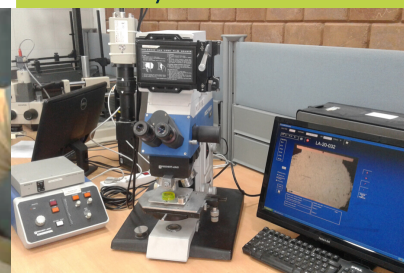
Dry heat Oven



Chemical Resistance Tests



NEW
PCB/PCBA Tests



CONTACT US

Email : chaima.khiari@actia-engineering.tn (Qualification Team Leader)
nizar.dhouib@actia-engineering.tn (Cross Section Technical Leader)

Phone : [+216 70 68 79 17](tel:+21670687917)

Web : <http://www.actia.com>

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